Vishay Siliconix

P-Channel 30 V (D-S) MOSFET



PRODUCT SUMMARY					
V _{DS} (V)	-30				
$R_{DS(on)}$ max. (Ω) at $V_{GS} = -10 \text{ V}$	0.0055				
$R_{DS(on)}$ max. (Ω) at $V_{GS} = -4.5 \text{ V}$	0.0093				
Q _g typ. (nC)	36				
I _D (A)	-60 ^{a, g}				
Configuration	Single				

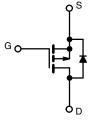
FEATURES

- TrenchFET® Gen III p-channel power MOSFET
- 100 % R_g and UIS tested
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



APPLICATIONS

- · Adapter and charger switch
- · Load switch
- Battery management



P-Channel MOSFET

ORDERING INFORMATION	
Package	PowerPAK SO-8
Lead (Pb)-free and halogen-free	SiR167DP-T1-GE3

ABSOLUTE MAXIMUM RATING	iS (Τ _A = 25 °C, ι	ınless otherwise	noted)		
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-source voltage		V _{DS}	-30	V	
Gate-source voltage		V _{GS}	± 25		
Continuous drain current (T _J = 150 °C)	T _C = 25 °C		-60 ^a		
	T _C = 70 °C		-60 ^a		
	T _A = 25 °C	I _D	-23.8 ^{b, c}		
	T _A = 70 °C		-19.1 ^{b, c}		
Pulsed drain current (t = 100 µs)		I _{DM}	-120	A	
Continuous accuracy during displacement	T _C = 25 °C		-54.8		
Continuous source-drain diode current	T _A = 25 °C	l _s	-4.2 ^{b, c}		
Single pulse avalanche current	. 0.1	I _{AS}	-20		
Single pulse avalanche energy L = 0.1 mH		E _{AS}	20	mJ	
	T _C = 25 °C		65.8		
Maritim and a superior designation of the contract of the cont	T _C = 70 °C		42.1	w	
Maximum power dissipation	T _A = 25 °C	P _D	5.1 ^{b, c}		
	T _A = 70 °C	1	3.2 b, c		
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +150		
Soldering recommendations (peak tempera		260	°C		

THERMAL RESISTANCE RAT	INGS				
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT
Maximum junction-to-ambient b	t ≤ 10 s	R _{thJA}	20	25	°C/W
Maximum junction-to-case (drain)	Steady state	R_{thJC}	1.5	1.9	C/W

Notes

- Package limited
 Surface mounted on 1" x 1" FR4 board
- See solder profile (www.vishay.com/doc?73257). The PowerPAK SO-8 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection
- Rework conditions: manual soldering with a soldering iron is not recommended for leadless components Maximum under steady state conditions is 65 °C/W
- $T_C = 25 \, ^{\circ}C$



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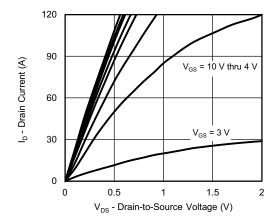
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static						•	
Drain-source breakdown voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	-30	-	-	V	
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	I _D = -10 mA	1	-25.8	-	>1/06	
V _{GS(th)} temperature coefficient	$\Delta V_{GS(th)}/T_J$	I _D = -250 μA	-	4.2	-	mV/°(
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	-1	-	-2.5	V	
Gate-source leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 25 \text{ V}$	=	-	100	nA	
Zoro goto voltago droin ourrent		$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}$	=	-	-1	μΑ	
Zero gate voltage drain current	I _{DSS}	V _{DS} = -30 V, V _{GS} = 0 V, T _J = 70 °C	-	-	-15		
On-state drain current ^a	I _{D(on)}	$V_{DS} \ge -10 \text{ V}, V_{GS} = -10 \text{ V}$	-30	-	-	Α	
Drain course on state registence ?	В	V _{GS} = -10 V, I _D = -15 A	-	0.0046	0.0055	5	
Drain-source on-state resistance ^a	R _{DS(on)}	V _{GS} = -4.5 V, I _D = -10 A	-	0.0078	0.0093	Ω	
Forward transconductance ^a	9 _{fs}	V _{DS} = -15 V, I _D = -20 A	=	60	-	S	
Dynamic ^b							
Input capacitance	C _{iss}		-	4380	-		
Output capacitance	C _{oss}	V _{DS} = -15 V, V _{GS} = 0 V, f = 1 MHz -			-	рF	
Reverse transfer capacitance	C _{rss}		-	460	-		
Total gata abaysa	0	$V_{DS} = -15 \text{ V}, V_{GS} = -10 \text{ V}, I_D = -23.8 \text{ A}$	-	74	111		
Total gate charge	Qg		=	36	54		
Gate-source charge	Q_{gs}	V _{DS} = -15 V, V _{GS} = -4.5 V, I _D = -23.8 A		12.1	-	nC	
Gate-drain charge	Q_{gd}		-	12.3	-		
Gate resistance	R_g	f = 1 MHz	0.32	1.6	3.2	Ω	
Turn-on delay time	t _{d(on)}		ı	20	40		
Rise time	t _r	$V_{DD} = -15 \text{ V}, R_L = 0.79 \Omega, I_D \cong -19.1 \text{ A},$	ī	25	50		
Turn-off delay time	t _{d(off)}	V_{GEN} = -10 V, R_g = 1 Ω	1	35	70		
Fall time	t _f		ı	18	36	ns	
Turn-on delay time	t _{d(on)}		ī	25	50	115	
Rise time	t _r	$V_{DD} = -15 \text{ V}, R_L = 0.79 \Omega, I_D \cong -19.1 \text{ A},$	-	25	50		
Turn-off delay time	t _{d(off)}	$V_{GEN} = -4.5 \text{ V}, R_g = 1 \Omega$	ı	35	70		
Fall time	t _f			22	44		
Drain-Source Body Diode Characteristi	cs						
Continuous source-drain diode current	Is	T _C = 25 °C	=	-	-54.8	Α	
Pulse diode forward current	I _{SM}				-120	_ ^	
Body diode voltage	V_{SD}	I _S = -5 A, V _{GS} = 0 V	ı	-0.73	-1.2	V	
Body diode reverse recovery charge	Q _{rr}	10.4.0 11/11/11/11	ı	45	90	nC	
Reverse recovery fall time	t _a	I _F = -19.1 A, di/dt = 100 A/μs,	-	19	-		
Reverse recovery rise time	t _b	T _J = 25 °C		22	-	ns	

Notes

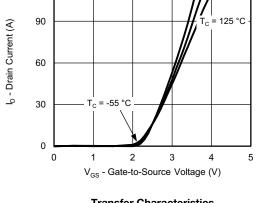
- a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %
- b. Guaranteed by design, not subject to production testing

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.





Output Characteristics

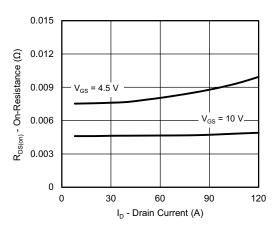


T_C = 25 °C

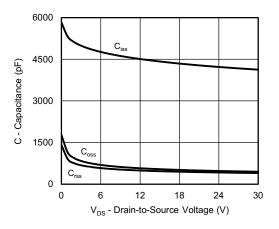
120

1.7

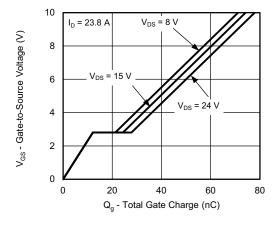
Transfer Characteristics



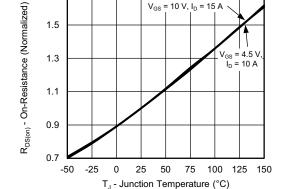
On-Resistance vs. Drain Current and Gate Voltage



Capacitance

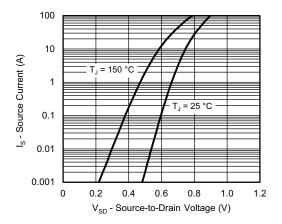


Gate Charge

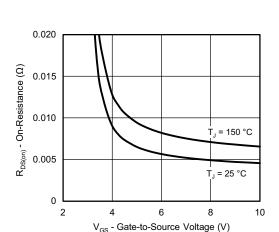


On-Resistance vs. Junction Temperature

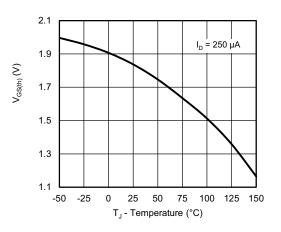




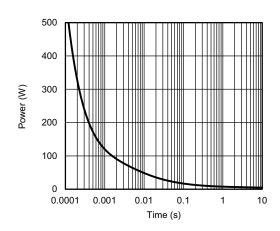
Source-Drain Diode Forward Voltage



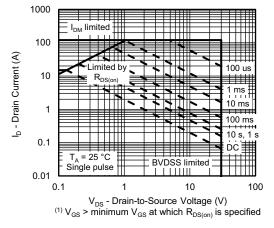
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage

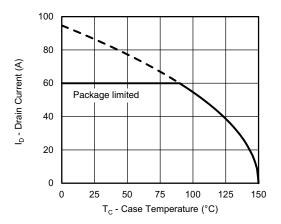


Single Pulse Power, Junction-to-Ambient

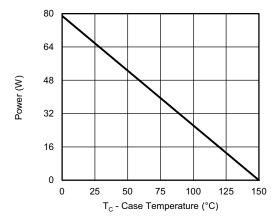


Safe Operating Area, Junction-to-Ambient

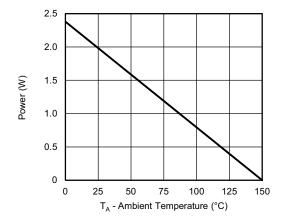




Current Derating a





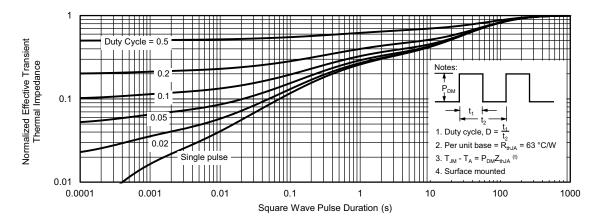


Power, Junction-to-Ambient

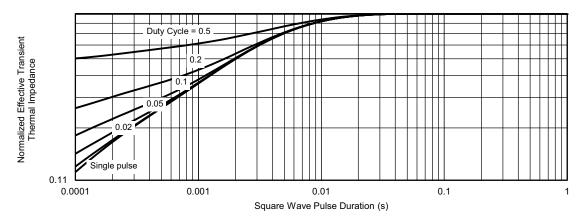
Note

a. The power dissipation P_D is based on T_J max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit





Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package / tape drawings, part marking, and reliability data, see www.vishay.com/ppg?76017.



DWG: 5881

PowerPAK® SO-8, (Single/Dual)

Notes 1. Inch will govern. 2 Dimensions exclusive of mold gate burrs.

3. Dimensions exclusive of mold flash and cutting burrs.

Backside View of Dual Pad

DIM		MILLIMETERS			INCHES			
DIM.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.		
Α	0.97	1.04	1.12	0.038	0.041	0.044		
A1		-	0.05	0	-	0.002		
b	0.33	0.41	0.51	0.013	0.016	0.020		
С	0.23	0.28	0.33	0.009	0.011	0.013		
D	5.05	5.15	5.26	0.199	0.203	0.20		
D1	4.80	4.90	5.00	0.189	0.193	0.197		
D2	3.56	3.76	3.91	0.140	0.148	0.15		
D3	1.32	1.50	1.68	0.052	0.059	0.06		
D4		0.57 typ.			0.0225 typ.			
D5		3.98 typ.			0.157 typ.			
E	6.05	6.15	6.25	0.238	0.242	0.24		
E1	5.79	5.89	5.99	0.228	0.232	0.23		
E2	3.48	3.66	3.84	0.137	0.144	0.15		
E3	3.68	3.78	3.91	0.145	0.149	0.15		
E4		0.75 typ.			0.030 typ.			
е		1.27 BSC			0.050 BSC			
K		1.27 typ.			0.050 typ.			
K1	0.56	-	-	0.022	-	-		
Н	0.51	0.61	0.71	0.020	0.024	0.02		
L	0.51	0.61	0.71	0.020	0.024	0.02		
L1	0.06	0.13	0.20	0.002	0.005	0.00		
θ	0°	-	12°	0°	-	12°		
W	0.15	0.25	0.36	0.006	0.010	0.01		
М	0.125 typ.				0.005 typ.			

Revison: 13-Feb-17 1 Document Number: 71655



RECOMMENDED MINIMUM PADS FOR PowerPAK® SO-8 Single



Recommended Minimum Pads Dimensions in Inches/(mm)

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APPLICATION NOTE



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